

AMENDMENTS TO THE SPECIFICATION

On page 1, prior to the BACKGROUND OF THE INVENTION, please insert the following paragraph:

5 **CROSS-REFERENCES TO RELATED APPLICATIONS**

This application is the US national phase of International Application PCT/JP2004/015053 filed October 13, 2004, which designated the US. PCT/JP2004/015053 claims priority to JP Patent Applications No. 2003-376967 filed November 6, 2003 and No. 2004-232371 filed August 9, 2004. The entire 10 contents of these applications are incorporated herein by reference.

Please amend paragraph [0005] beginning at line 2, page 3, as follow

[0005] ~~In order to accomplish the object, there is provided an~~ An optical device package structure, ~~including according to an aspect of the present invention includes:~~

15 an optical device;

 a lead frame having a mounting portion on which the optical device is mounted and a lead portion electrically connected to the optical device, ~~the mounting portion having an aperture through which light incident on or emitted from the optical device passes;~~

20 a wire placed on a side of the lead frame on which side the optical device is mounted and electrically connecting the optical device with the lead portion;

~~a first resin placed on a side opposite from the side of the lead frame on which the optical device is mounted, the first resin being transmissive to~~

the light and through which light incident on or emitted from the optical device passes; and

a second resin at least part of which is placed on the side of the lead frame on which the optical device is mounted, the second resin sealing the optical device and the wire and having a coefficient of linear expansion lower than that of the first resin; and

 a crack prevention structure preventing the first resin from cracking.

Please amend paragraph [0007] beginning at line 8, page 4, as follows:

10 **[0007]** MoreoverIn various embodiments, the optical device package
structure further includes a crack prevention structure preventing the first resin
from cracking. In this case, despite that the coefficient of linear expansion of
the first resin is greater than the coefficient of linear expansion of the lead frame
and so on, it becomes difficult to cause cracks in the first resin by virtue of the
15 crack prevention structure. Therefore, even if the structure is used in an
environment where the temperature change is comparatively large, the problem
of the generation of cracks in the first resin is effectively prevented.